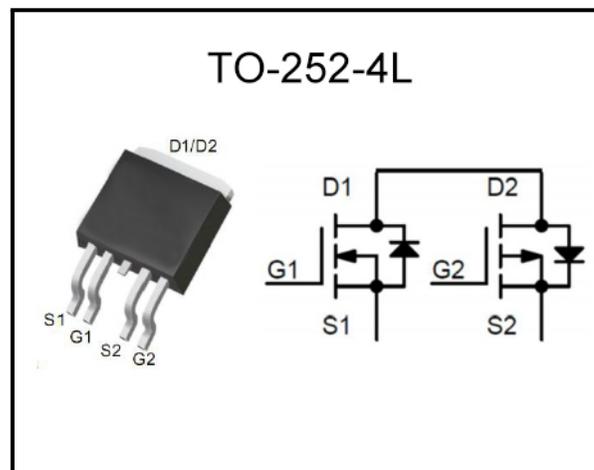


### Features

- **N-Channel:**
- $V_{DS}=40V, I_D=30A$
- $R_{DS(ON)}@V_{GS}=10V, I_D=8A, TYP=12m\Omega$
- $R_{DS(ON)}@V_{GS}=4.5V, I_D=4A, TYP=17m\Omega$
- **P-Channel:**
- $V_{(BR)DSS}=-40V, I_D=-18A$
- $R_{DS(ON)}@V_{GS}=-10V, I_D=-8A, TYP=28m\Omega$
- $R_{DS(ON)}@V_{GS}=-4.5V, I_D=-4A, TYP=38m\Omega$

### Package



### General Description

Complementary Enhancement MOSFET in a TO-252-4L Package. The BMI404D1538 uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge can be used in a wide variety of applications.

### Applications

- Power factor correction (PFC)
- Uninterruptible power supply (UPS)
- Switched mode power supplies (SMPS)
- LED lighting power

### Absolute Maximum Ratings ( $T_J=25^\circ C$ unless otherwise specified)

Symbol	Parameter	N-Channel	P-Channel	Units
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	40	-40	V
$V_{GS}$	Gate - Source Voltage	$\pm 20$	$\pm 20$	V
$I_D$	Continuous Drain Current	30	-18	A
$I_{DM}$	Pulse Drain Current <sup>(1)</sup>	120	-72	A
$P_D$	Power Dissipation	35		W
$T_J, T_{stg}$	Junction and Storage temperature range	-55 to +150		$^\circ C$
$T_L$	Max. lead temperature for soldering purposes, 1/8" from case for 5 seconds	300		$^\circ C$
$R_{\theta JC}$	Thermal Resistance From Junction to Case	3.5		$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance from Junction to Ambient	62.5		$^\circ C/W$



### N-Channel Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
<b>Static Electrical Characteristics</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0, I <sub>D</sub> =250uA	40	–	–	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 40V, V <sub>GS</sub> =0	–	–	1	uA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> =0	–	–	±100	nA
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> =250uA	1.5	1.9	2.5	V
Static Drain-source On Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =8A	–	12	15	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =4A	–	17	25	
Forward Transconductance	g <sub>fs</sub>	V <sub>DS</sub> =5V, I <sub>D</sub> =10A	10	14.7	20	S
<b>Dynamic Electrical Characteristics</b>						
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, f = 1MHz	–	1512	–	pF
Output capacitance	C <sub>oss</sub>		–	208	–	
Reverse transfer capacitance	C <sub>rss</sub>		–	142	–	
Gate to Drain Charge	Q <sub>g</sub>	V <sub>DS</sub> =20V, V <sub>GS</sub> =10V, I <sub>D</sub> =10A <sup>(2,3)</sup>	–	23	–	nC
Gate to Source Charge	Q <sub>gs</sub>		–	5.1	–	
Gate to Drain Charge	Q <sub>gd</sub>		–	4.6	–	
<b>Switching Characteristics</b>						
Turn-on delay time	T <sub>d(on)</sub>	V <sub>DD</sub> =20V, V <sub>GS</sub> =10V, R <sub>G</sub> =3Ω <sup>(2,3)</sup>	–	5.8	–	ns
Turn-on Rise time	T <sub>r</sub>		–	12.5	–	
Turn -Off Delay Time	T <sub>d(off)</sub>		–	21	–	
Turn -Off Fall time	T <sub>f</sub>		–	6.7	–	
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =10A	–	0.86	1.4	V
Continuous Source Current	I <sub>S</sub>	Integral Reverse P-N Junction Diode in the MOSFET	–	–	30	A
Pulsed Source Current	I <sub>SM</sub>		–	–	120	

Notes:

- (1) Pulse width limited by maximum junction temperature.
- (2) Pulse Test: Pulse width ≤ 300μs, Duty cycle ≤ 2%.
- (3) Essentially independent of operating temperature.



### P-Channel Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
<b>Static Electrical Characteristics</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250uA	-40	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = -40V, V <sub>GS</sub> = 0V	-	-	-1	uA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V	-	-	±100	nA
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = -250uA	-1.5	-1.9	-2.4	V
Static Drain-source On Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> = -10V, I <sub>D</sub> = -8A	-	28	38	mΩ
		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -4A	-	38	52	
Forward Transconductance	g <sub>fs</sub>	V <sub>DS</sub> = -5V, I <sub>D</sub> = -10A	12	16.8	22	S
<b>Dynamic Electrical Characteristics</b>						
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V, f = 1MHz	-	1217	-	pF
Output capacitance	C <sub>oss</sub>		-	198	-	
Reverse transfer capacitance	C <sub>rss</sub>		-	125	-	
Gate to Drain Charge	Q <sub>g</sub>	V <sub>DS</sub> = -20V, V <sub>GS</sub> = -10V, I <sub>D</sub> = -7A <sup>(2,3)</sup>	-	23.5	-	nC
Gate to Source Charge	Q <sub>gs</sub>		-	3.7	-	
Gate to Drain Charge	Q <sub>gd</sub>		-	3.1	-	
<b>Switching Characteristics</b>						
Turn-on delay time	T <sub>d(on)</sub>	V <sub>DD</sub> = -20V, V <sub>GS</sub> = -10V, R <sub>G</sub> = 6.0Ω <sup>(2,3)</sup>	-	11.5	-	ns
Turn-on Rise time	T <sub>r</sub>		-	13.8	-	
Turn -Off Delay Time	T <sub>d(off)</sub>		-	32.7	-	
Turn -Off Fall time	T <sub>f</sub>		-	17.9	-	
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0V, I <sub>S</sub> = -10A	-	-0.91	-1.4	V
Continuous Source Current	I <sub>S</sub>	Integral Reverse P-N Junction Diode in the MOSFET	-	-	-18	A
Pulsed Source Current	I <sub>SM</sub>		-	-	-72	

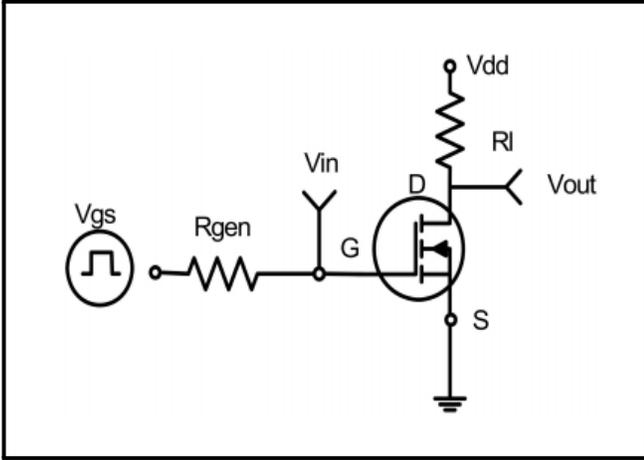
Notes:

- (1) Pulse width limited by maximum junction temperature.
- (2) Pulse Test: Pulse width ≤ 300μs, Duty cycle ≤ 2%.
- (3) Essentially independent of operating temperature.

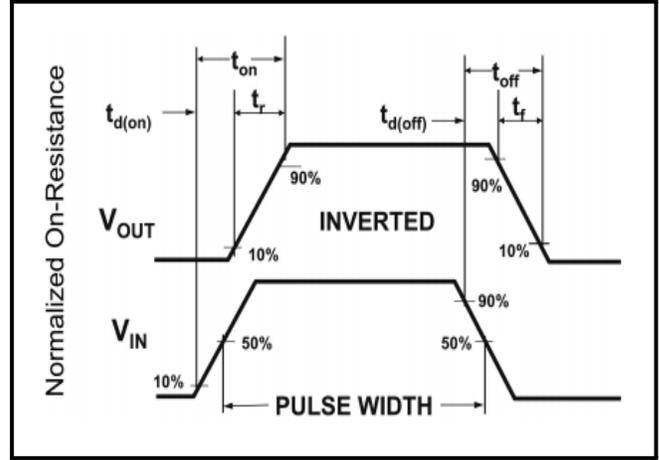


**N-Channel Typical Characteristics**

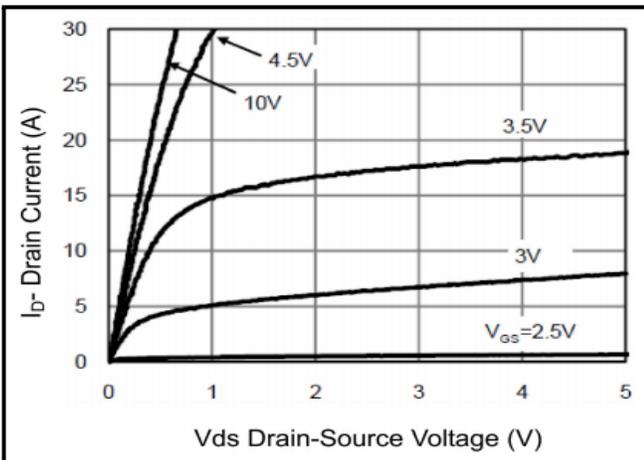
**Figure 1: Switching Test Circuit**



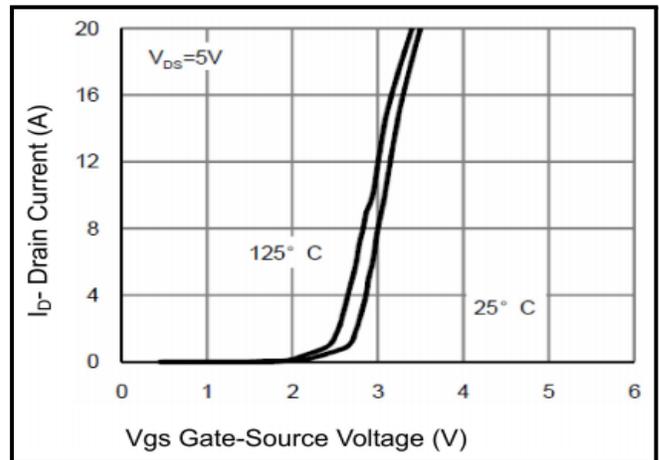
**Figure 2: Switching Waveforms**



**Figure 3: Output Characteristics**

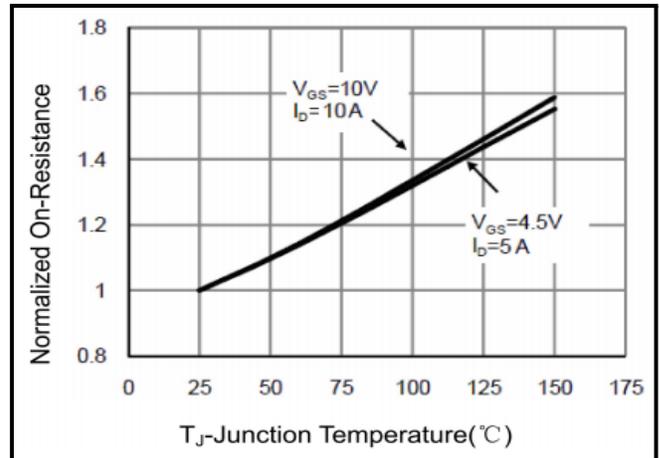
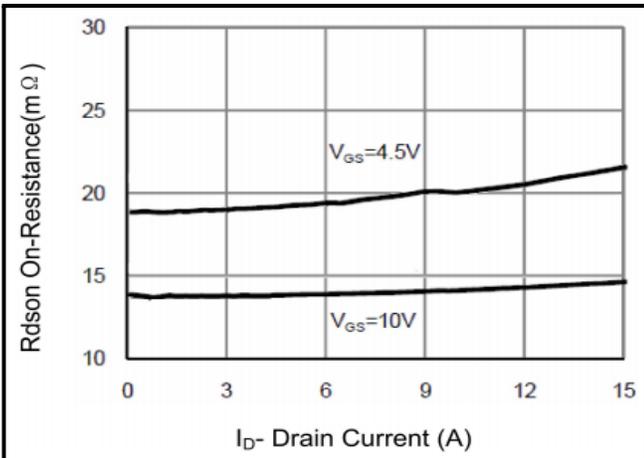


**Figure 4: Transfer Characteristics**



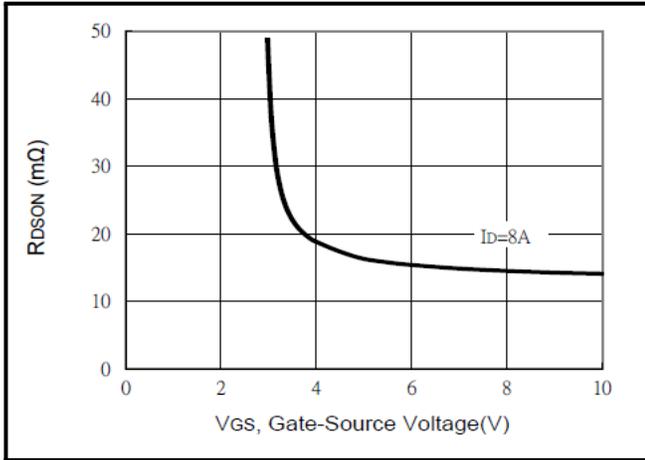
**Figure 5: Drain-Source On-Resistance vs ID**

**Figure 6: Drain-Source On-Resistance vs Tj**

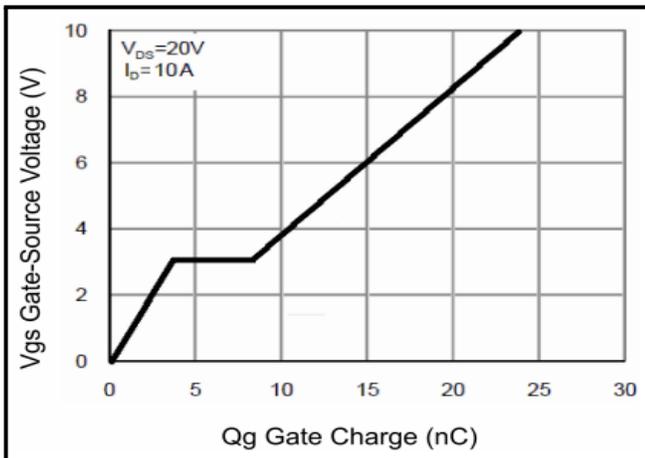


**N-Channel Typical Characteristics**

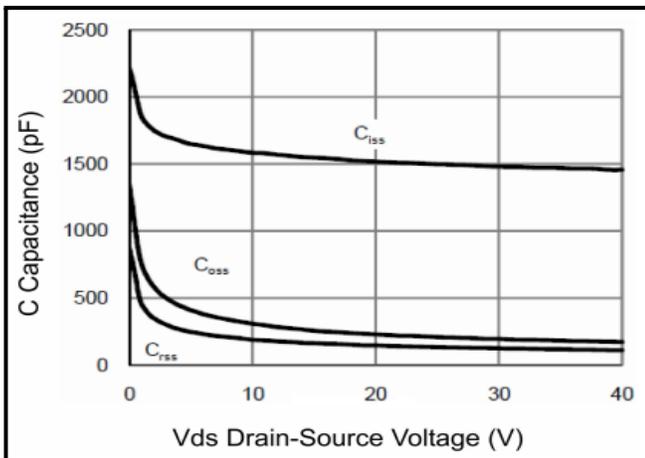
**Figure 7:  $R_{DS(ON)}$  vs  $V_{GS}$**



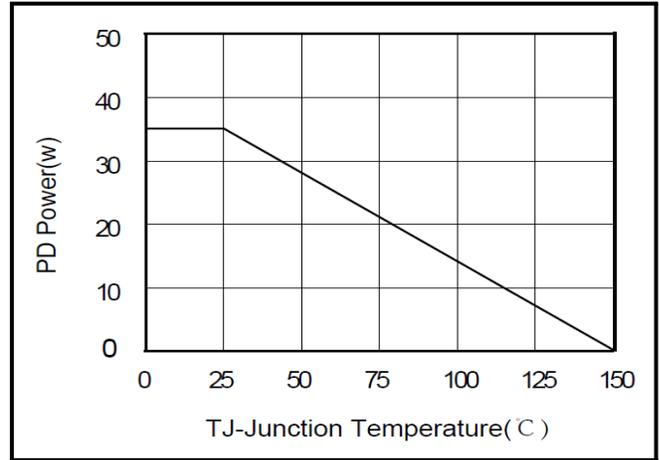
**Figure 9: Gate Charge**



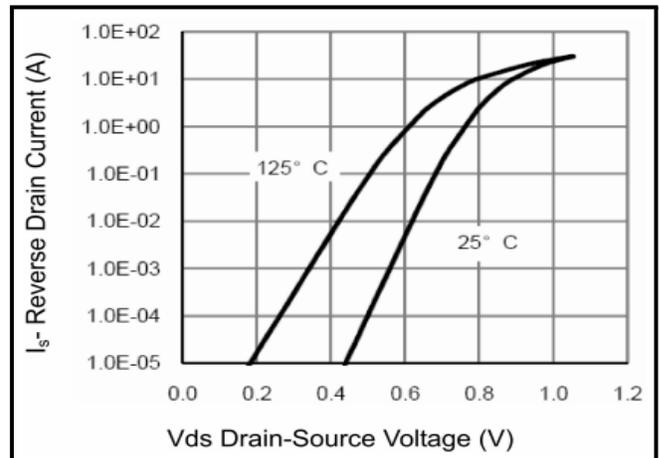
**Figure 11: Capacitance vs  $V_{DS}$**



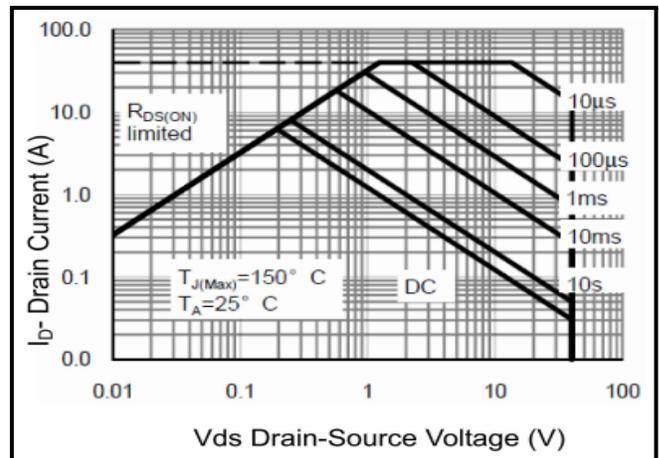
**Figure 8: Power Dissipation**



**Figure 10: Source-Drain Diode Forward**

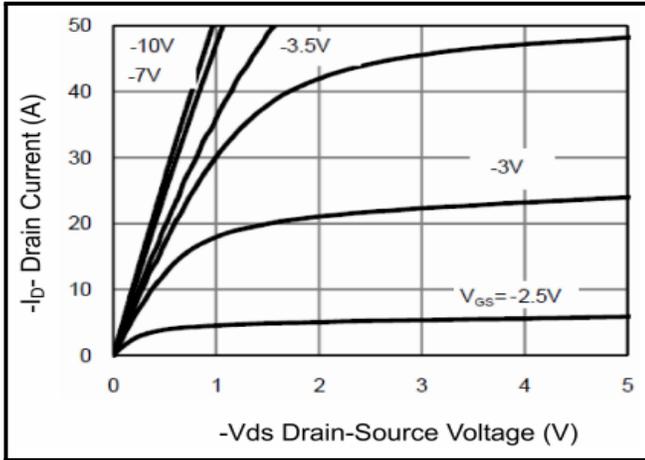


**Figure 12: Safe Operation Area**

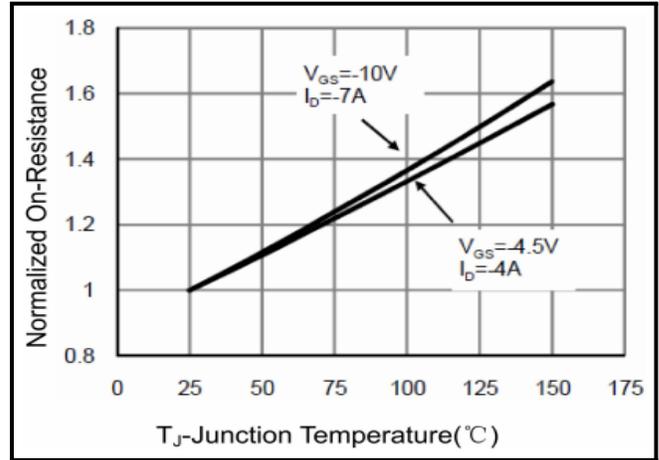


**P-Channel Typical Characteristics**

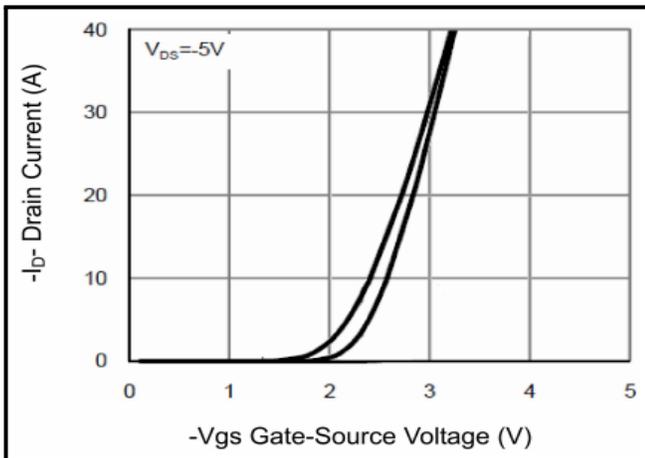
**Figure 1: Output Characteristics**



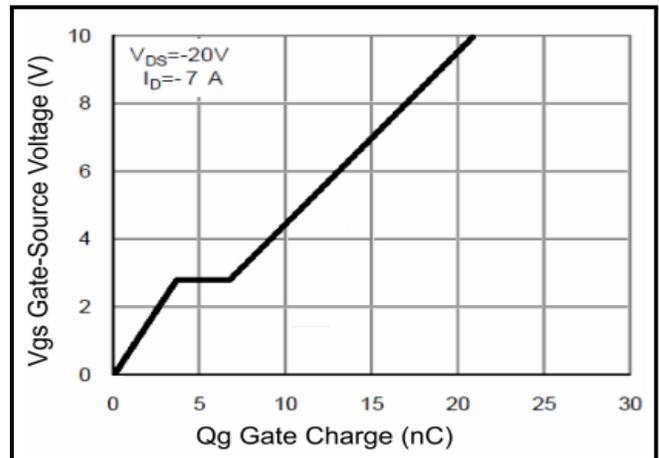
**Figure 2:  $R_{DS(ON)}$  vs Junction Temperature**



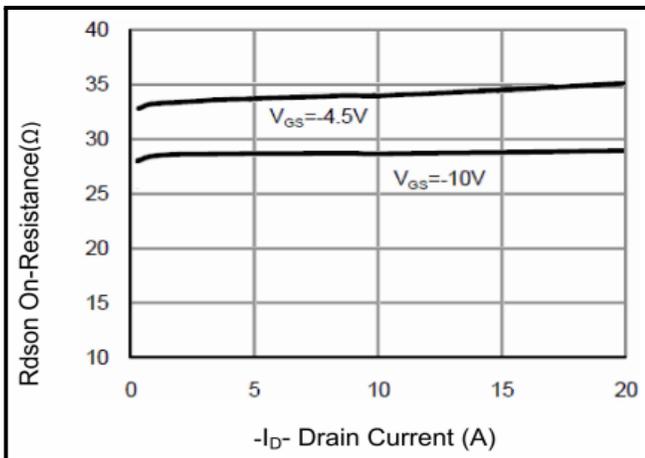
**Figure 3: Transfer Characteristics**



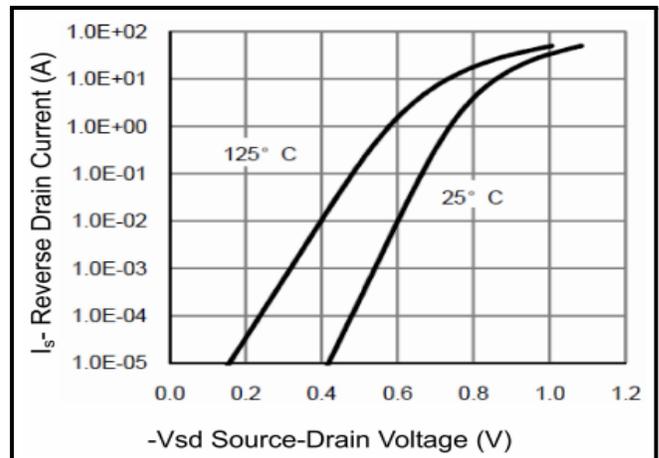
**Figure 4: Gate Charge**



**Figure 5:  $R_{DS(ON)}$  vs Drain Current**

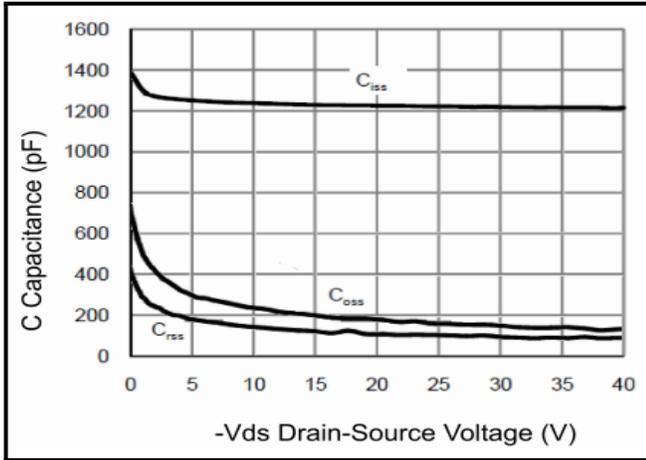


**Figure 6: Source-Drain Diode Forward**

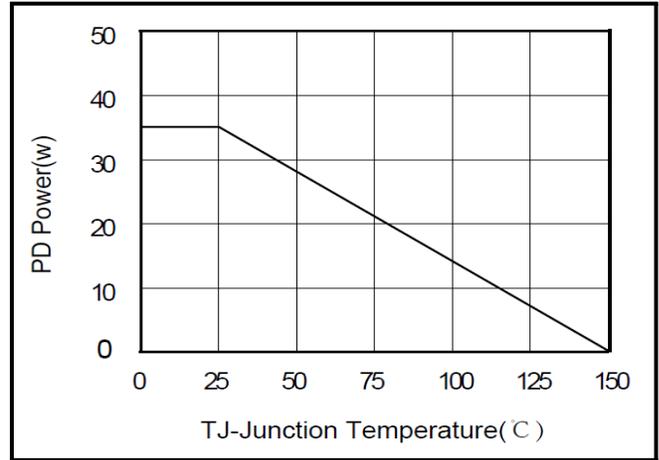


**P-Channel Typical Characteristics**

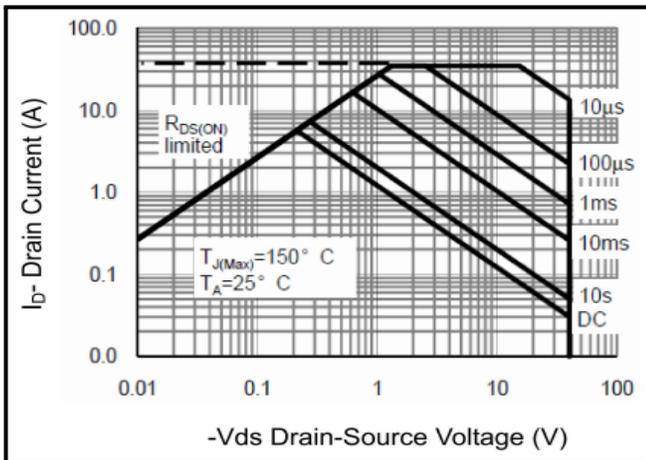
**Figure 7: Capacitance vs  $V_{DS}$**



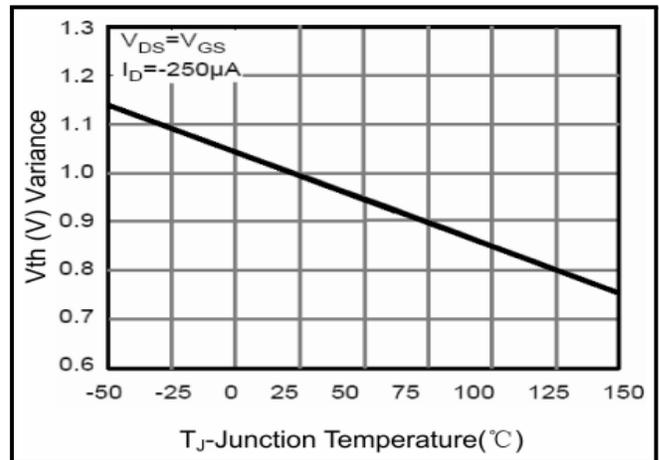
**Figure 8: Power Dissipation**



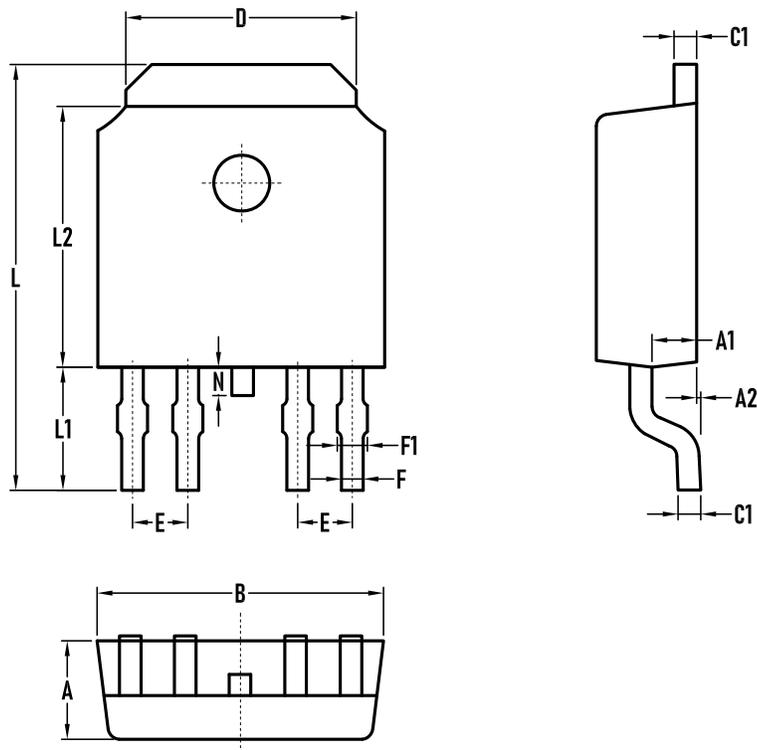
**Figure 9: Safe Operation Area**



**Figure 10:  $V_{GS(th)}$  vs Junction Temperature**



**Packaging Tape - TO-252-4L**



SYMBOL	MIN	TYP	MAX
A	2.20	2.30	2.40
A1	0.90	1.00	1.10
A2	0.05	0.15	0.20
B	6.50	6.60	6.70
C	0.46	0.50	0.54
C1	0.46	0.50	0.54
D	5.22	5.32	5.42
E	1.27 typ.		
F	0.40	0.50	0.60
F1	0.50	0.60	0.70
L	9.77	9.97	10.17
L1	2.67	2.87	3.07
L2	6.02	6.10	6.18
N	0.55	0.65	0.75

